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Datasheet MSD30AG

Version 3.10

Datasheet



REVISION HISTORY

Version	Date	Notes	Approver
1.0	11/13/09	Initial version	Andrew Chen
1.01	11/17/09	Revised pin names and definitions.	Andrew Chen
1.02	12/15/09	Updated Power Consumption values for Specifications table.	Andrew Chen
1.03	01/04/10	Revised Operational Description. Added Regulatory section.	Andrew Chen
1.04	01/29/10	Revised mechanical drawing and Specs table. Revised pin names and definitions.	Andrew Chen
1.05	04/16/10	Added RF Layout Guidelines section.	Andrew Chen
1.06	05/04/10	Revised pinouts and antenna information.	Andrew Chen
1.07	06/11/10	Added I/O signal details.	Andrew Chen
1.08	08/24/10	Updated images; added SDIO Interface Timing information; revised pin definitions	Andrew Chen
1.09	09/28/10	Updated block diagram.	Andrew Chen
1.10	01/12/11	Updated mechanical drawing.	Andrew Chen
2.0	04/05/11	Corrections to BT pins on Pinout table.	Andrew Chen
2.1	04/15/11	Revised Block Diagram.	Andrew Chen
2.2	07/06/11	No released	Andrew Chen
2.3	07/19/11	Updated mechanical drawings	Andrew Chen
2.4	10/05/11	Added MSD30AG/MSD40NBT Pin Comparison table. Added MSD30AG/T-board image. Added MSD30AG schematic.	Andrew Chen
2.5	10/19/11	Corrected mechanical drawing.	Andrew Chen
3.0	09/10/12	Updated the following Pin descriptions: WLAN_ACTIVE (28), BT_ACTIVE (36).	Andrew Chen
3.1	10/02/12	Updated Mounting section with revised spacer information.	Andrew Chen
3.2	1/31/13	Updated 5 GHz Frequencies and Operating Channels	Andrew Chen
3.3	14 Oct 2013	Removed all references to summitdata.com	Sue White
3.4	19 Mar 2014	Add note regarding the following pins: CHIP_PWD_L, SYS_RST_L, BT_RST_L, VDDIO_DR	Andrew Chen
3.5	23 Oct 2015	Removed internal links; added Approved By column to Revision History	Sue White
3.6	20 Sept 2016	Added EU Declaration of Conformity	Sue White
3.7	19 Apr 17	Added MIC Requirements	Sue White
3.8	03 May 2017	Updated CE/EU Declaration of Conformity section	Maggie Teng
3.9	05 June 2017	Updated the EU DoC for new RED standards	Tom Smith
3.10	20 June 2017	Fixed error on EU DoC (Changed to EU Directive 2014/53/EU) EN 301 893 v2.1.0 (2017-03) to EN 301 893 v2.1.1 (2017-05)	Tom Smith

Datasheet



CONTENTS

Scope	4
Block Diagram	
Specifications	5
DC Electrical Characteristics	9
SDIO Timing Definitions	
Pin Definitions	
MSD30AG and MSD40NBT Pin Comparison Table	
Mechanical Specifications	
Connector Overview	
RF Layout Design Guidelines	
Regulatory	
Certified Antennas	
Documentation Requirements	
.1. FCC	
.2. Industry Canada	
.3. European Union	
.4. MIC	
Appendix A: Schematic	
Additional Assistance	
•	Operational Description Block Diagram Specifications DC Electrical Characteristics SDIO Timing Definitions Pin Definitions MSD30AG and MSD40NBT Pin Comparison Table Mechanical Specifications Connector Overview



1 Scope

This document describes key hardware aspects of the Summit MSD30AG 802.11a/b/g SDIO (Secure Digital Input/Output) radio module. This document is intended to assist device manufacturers and related parties with the integration of this radio into their host devices. Data in this document are drawn from a number of sources and includes information found in the Atheros AR6002 data sheet.

Contact Laird or visit the MSD30AG page at lairdtech.com for the most recent version of this document.

2 OPERATIONAL DESCRIPTION

This device is an SDC-MSD30AG 802.11a/g SDIO (Secure Digital Input/Output) radio module which operates in unlicensed portions of the 2.4 GHz and 5 GHz radio frequency spectrum. The device is compliant with IEEE 802.11a, 802.11b, and 802.11g standards using Direct Sequence Spread Spectrum (DSSS) and Orthogonal Frequency Division Multiplexing (OFDM). The device supports all 802.11a, 802.11b, and 802.11g data rates and automatically adjusts data rates and operational modes based on various environmental factors.

When operating on channels in the UNII-2 and UNII-2 extended bands that are in the 5 GHz portion of the frequency spectrum and are subject to Dynamic Frequency Selection (DFS) requirements, the SDC-MSD30AG fully conforms to applicable regulatory requirements. In the event that specified types of radar are detected by the network infrastructure, the SDC-MSD30AG fully conforms to commands from the infrastructure for radar avoidance.

The SDC-MSD30AG interfaces to host devices via a 60-pin connector. The device is based on the Atheros AR6002 chip which is an integrated device providing a Media Access Controller (MAC), a Physical Layer Controller (PHY or baseband processor), and 2.4 GHz and 5 GHz transceivers. To maximize operational range, the SDC-MSD30AG incorporates 2.4 GHz and 5 GHz power amplifiers (PA) to increase transmit power to as much as 18 dBm (63 mW) and a 5 GHz low-noise amplifier (LNA) to improve receiver sensitivity. The frequency stability for both 2.4 GHz (802.11b and 802.11g) and 5 GHz (802.11a) operation is +/- 20 ppm. The SDC-MSD30AG is powered by the host device into which it is installed. The SDC-MSD30AG supports dual band transmit and receive diversity. Supported host device antenna types include dipole and monopole antennas.

The SDC-MSD30AG has its own RF shielding and does not require shielding provided by the host device into which it is installed in order to maintain compliance with applicable regulatory standards. As such, the device may be tested in a standalone configuration via an extender card. The device buffers all data inputs so that it will comply with all applicable regulations even in the presence of over-modulated input from the host device. Similarly, the SDC-MSD30AG incorporates power regulation to comply with all applicable regulations even when receiving excess power from the host device.

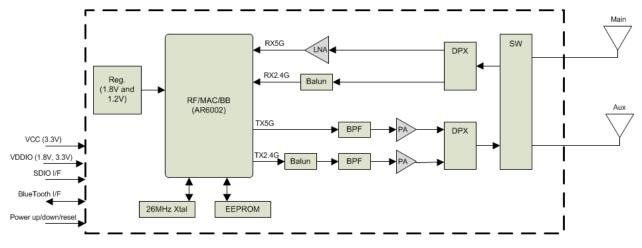
The SDC-MSD30AG provides two unique U.FL type antenna connectors to allow for diversity support when operating in 802.11a, 802.11b and 802.11g modes. The device is labeled with all applicable regulatory information in a manner that's compliant with all regulatory standards. Regulatory operational requirements are included with this document and they may be incorporated into the operating manual of any device into which the SDC-MSD30AG is installed. The SDC-MSD30AG is designed for installation into mobile devices such as vehicle mount data terminals (which typically operate at distances greaterthan 20 cm from the human body) and portable devices such as handheld data terminals (which typically operate at distances less than 20 cm from the human body). See "Documentation Requirements" for more information.

Datasheet



3 BLOCK DIAGRAM

The block diagram for the SDC-MSD30 is as follows:



4 SPECIFICATIONS

Table 1: Specifications

Feature	Description					
System Interface	1-bit or 4-bit Secure Digital I/O					
Physical Interface	Molex 54722-0607 60-pin connector (r connector)	Molex 54722-0607 60-pin connector (mates to Molex 55560-0607 60-pin connector)				
Antenna Interface	2 Hirose U.FL connectors for dual-band	d antenna diversity				
Chip Set	Atheros AR6002					
Input Voltage Requirements	3.3 VDC ± 10% (core)					
I/O Signaling Voltage	3.3 VDC ± 10%					
Current Consumption (At maximum transmit power setting)	802.11a Transmit: 380 mA (1254 mW) Receive: 115 mA (380 mW) Standby: 3 mA (10 mW)	802.11b/g Transmit: 325 mA (1072 mW) Receive: 95 mA (314 mW) Standby: 2 mA (7 mW)				
Operating Temperature	-25° to 70°C (-13° to 158°F) Note: The MSD30AG is rated down to - connector is rated to -25°.	-25° (not -30°) because the Molex				
Operating Humidity	10 to 90% (non-condensing)					
Storage Temperature	-30° to 85°C (-22° to 185°F)					
Storage Humidity	10 to 90% (non-condensing)					
Length	32 mm (1.26 in.)					
Width	22 mm (0.87 in.)					
Thickness	4.5 mm (0.18 in.) Note: With the mating connector, the plugs into.	thickness is 5.1 mm above the board it				

Datasheet



Feature	Description					
Weight	3.0 g (0.11 oz.)	3.0 g (0.11 oz.)				
Mounting	3 mounting holes (2.36 mm, 0.093	3 mounting holes (2.36 mm, 0.093 in.)				
Wi-Fi Wireless Media	Direct Sequence-Spread Spectrum	(DSSS)				
	Orthogonal Frequency Divisional N	Iultiplexing (OFDM)				
Wi-Fi Media Access Protocol	Carrier sense multiple access with o	collision avoidance (CSMA/CA)				
Network Architecture Types	Infrastructure and ad hoc					
Network Standards	IEEE 802.11a, 802.11b, 802.11d, 80	2.11e, 802.11g, 802.11h, 802.11i				
Wi-Fi Data Rates Supported	802.11a (OFDM) 6, 9, 12, 18, 24, 36 802.11b (DSSS) 1, 2, 5.5, 11 Mbps 802.11g (OFDM) 6, 9, 12, 18, 24, 36					
Wi-Fi Modulation	BPSK @ 1, 6, and 9 Mbps QPSK @ 2, 12, and 18 Mbps CCK @ 5.5 and 11 Mbps 16-QAM @ 24 and 36 Mbps 64-QAM @ 48 and 54 Mbps	QPSK @ 2, 12, and 18 Mbps CCK @ 5.5 and 11 Mbps 16-QAM @ 24 and 36 Mbps				
Regulatory Domain Support	-					
2.4 GHz Frequency Bands	ETSI	MIC				
	2.4 GHz to 2.483 GHz	2.4 GHz to 2.495 GHz				
	FCC	КСС				
	2.4 GHz to 2.473 GHz	2.4 GHz to 2.483 GHz				
5 GHz Frequency Bands	ETSI	MIC				
	5.15 GHz to 5.35 GHz	5.15 GHz to 5.35 GHz				
	5.47 GHz to 5.725 GHz	КСС				
	FCC	5.15 GHz to 5.35 GHz				
	5.15 GHz to 5.35 GHz 5.47 GHz to 5.725 GHz 5.725 GHz to 5.82 GHz	5.725 GHz to 5.82 GHz				
2.4 GHz Operating Channels	ETSI: 13 (3 non-overlapping) FCC: 11 (3 non-overlapping)	MIC 14 (4 non-overlapping) KCC: 13 (3 non-overlapping)				
5 GHz Operating Channels	ETSI: 19 non-overlapping FCC: 23 non-overlapping	MIC: 8 non-overlapping KCC: 12 non-overlapping				

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Datasheet



Feature	Description					
Wi-Fi Transmit Power Settings	802.11a		802.11g			
	15 dBm (30 mW)		18 dBm (63 mW)			
Note: Maximum transmit power	13 dBm (20		17 dBm (50			
varies according to individual	10 dBm (10		15 dBm (30			
country regulations. All values		,		13 dBm (20 mW)		
nominal, +/-2 dBm	802.11b		10 dBm (10			
	18 dBm (63		7 dBm (5 m			
	17 dBm (50		0 dBm (1 m			
	15 dBm (30		0 0011 (1 1	,		
	13 dBm (20					
	10 dBm (10					
	7 dBm (5 r	nW)				
	0 dBm (1 r	nW)				
Typical Receiver Sensitivity	802.11a			802.11b		
	6 Mbps	-85 dBm		1 Mbps	-95 dBm	
Note: All values nominal, +/-3 dBm.	9 Mbps	-83 dBm		2 Mbps	-94 dBm	
	12 Mbps	-83 dBm		5.5 Mbps	-93 dBm	
	18 Mbps	-81 dBm		11 Mbps	-89 dBm (PER <= 10%)	
	24 Mbps	-75 dBm				
	36 Mbps	-73 dBm				
	48 Mbps	-68 dBm				
	54 Mbps -67 dBm (PER		R <= 10%)			
	802.11g					
	6 Mbps	-93 dBm				
	12 Mbps	-88 dBm				
	18 Mbps	-85 dBm				
	24 Mbps	-83 dBm				
	36 Mbps	-77 dBm				
	48 Mbps	-74 dBm				
	54 Mbps	-72 dBm (PEI	R <= 10%)			
Wi-Fi Delay Spread	600 ns @ 1	-		350 ns @ 12 l		
	500 ns @ 2	•		350 ns @ 18 ľ		
	400 ns @ 5	-	250 ns @ 24 Mbps			
	400 ns @ 6	-		250 ns @ 36 Mbps		
	400 ns @ 9 Mbps		150 ns @ 48 Mbps		•	
	200 ns @ 11 Mbps			150 ns @ 54 l	Vbps	
Mean Time Between Failure (MTBF)	1,345,685 ho					
Operating Systems Supported	Windows N				bedded CE 6.0 R3	
	Windows Mobile 6.1				bedded CE 6.0 R2	
	Windows N				bedded CE 6.0	
	Windows N	/lobile 5.0		Windows Emi	pedded CE 5.0	

Datasheet



Feature	Description
Security	Standards Wireless Equivalent Privacy (WEP) Wi-Fi Protected Access (WPA) IEEE 802.11i (WPA2) Encryption Wireless Equivalent Privacy (WEP, RC4 Algorithm) Temporal Key Integrity Protocol (TKIP, RC4 Algorithm) Advanced Encryption Standard (AES, Rijndael Algorithm) Encryption Key Provisioning Static (40-bit and 128-bit lengths) Pre-Shared (PSK) Dynamic 802.1X Extensible Authentication Protocol Types EAP-FAST EAP-FAST EAP-TLS PEAP-GTC PEAP-MSCHAPv2 PEAP-TLS LEAP
Compliance	ETSI Regulatory DomainFCC Regulatory DomainEN 300 328Part 15.247 Subpart CEN 301 489Part 15.407 Subpart EEN 301 893Industry CanadaEN60950-1RSS-210/RSS-Gen Issue 2EU 2002/95/EC (RoHS)MIC Regulatory DomainArticle 2 Item 19, Category WW (2.4 GHz Channels 1-13)Article 2 Item 19-2, Category GZ (2.4 GHz Channel 14)Article 2 Item 19-3, Category XW (5150-5250 W52 & 5250-5350 W53)Wi-Fi Alliance
	802.11a, 802.11b, 802.11g WPA Enterprise WPA2 Enterprise Cisco Compatible Extensions (Version 4)
Warranty	Limited Lifetime
All spe	cifications are subject to change without notice



5 DC ELECTRICAL CHARACTERISTICS

Table 2: DC Electrical Characteristics

Symbol	Parameter	Min	Тур	Max	Unit
VCC	DC Supply Voltage	3.0	3.3	3.6	V
lvcc	DC Supply Current, (max transmit power setting)			802.11a Transmit: 380 mA (1254 mW) Receive: 115 mA (380 mW) Standby: 3 mA (10 mW) 802.11b/g Transmit: 325 mA (1072 mW) Receive: 95 mA (314 mW) Standby: 2 mA (7 mW)	mA
VDDIO	Digital I/O Reference Voltage	-	-	-	V
Ivddio	Digital I/O Current		0.05	0.40	mA
VIH	High Level Input Voltage	0.8 x V _{DDIO}	-	V _{DDIO} + 0.3	V
VIL	Low Level Input Voltage	-0.3	-	0.2 x V _{DDIO}	V
Vон	High Level Output Voltage	V _{DDIO} – 0.35	-	-	V
Vol	Low Level Output Voltage	-	-	0.40	V
CIN	Input Capacitance	-	6	-	pF

The MSD30AG has an internal pull-down on CHIP_PWD_L, so when the host pulls it high, the pad sinks current. The amount of current depends on VDDIO. ~10 μ A for VDDIO = 1.8V and ~40 μ A when VDDIO = 3.3V. As a result, the solution power consumption is at least 18-132 μ W higher than the chip power consumption in non-CHIP_PWD states.

The analog power-on reset circuit in the MSD30AG is also optimizer for VDDIO = 1.8V, thus the chip draws an extra 3.5μ A when VDDIO = 3.3V. The MSD30AG has an internal pull-up on SYS_RST_L, thus to minimize CHIP_PWD power consumption, customer designs should not tie CHIP_PWD_L and SYS_RST_L together.

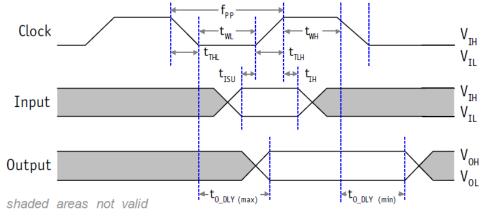


Figure 1: SDIO Interface Timing

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5.1. SDIO Timing Definitions

Table 3: SDIO timing definitions

Parameter	Description	Min	Max	Unit				
SDIO CLK (All values are r	SDIO CLK (All values are referred to minimum VIH and maximum VIL $^{ m b}$							
fpp	Clock frequency data transfer mode	0	25	MHz				
twL	Clock low time	10	-	ns				
twн	Clock high time	10	-	ns				
tтıн	Clock rise time	-	10	ns				
tтнL	Clock fall time	-	10	ns				
Inputs: CMD, Data (refere	enced to CLK)							
tisu	Input setup time	5	-	ns				
tıн	Input hold time	5	-	ns				
Outputs: CMD, Data (referenced to CLK)								
to_DLY (min)	Output delay time during data transfer mode	0	14	ns				
to_DLY (max)	Output delay time during data transfer mode	0	50	ns				

a.) Timing is based on CL \leq 40pF load on CMD and Data

b.) Min (Vih) = 0.7 x VDDIO and max (Vil) = 0.2 x VDDIO

6 Pin Definitions

Table 4: Pin Definitions

Pin Number	Pin Name	I/O	Power Supply	Description
1	GND			Ground
2	RSVD	N/C		Reserved – No Connect
3	BT_PRIORITY	I	VDDIO	Input from BT device. When high, indicates that Bluetooth is transmitting or receiving high priority packets, e.g. SCO and LMP. When not in use, leave open (float).
4	BT_FREQ	I	VDDIO	Input from BT device. When high, indicates that Bluetooth is operating on a channel used by WLAN (a restricted channel). BT_FREQ is not necessary when Bluetooth Adaptive Frequency Hopping is enabled. When not in use, leave open (float).
5	RSVD	N/C		Reserved – No Connect
6	RSVD	N/C		Reserved – No Connect
7	RSVD	N/C		Reserved – No Connect
8	WL_GPIO_1	0	VDDIO	Wake on Wireless. Internal pull-down. Wake on Wireless is not currently supported in the software. May be left open
9	RSVD	N/C		Reserved – No Connect

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Datasheet



Pin Number	Pin Name	ı/o	Power Supply	Description
10	RSVD	N/C		Reserved – No Connect
11	RSVD	N/C		Reserved – No Connect
12	RSVD	N/C		Reserved – No Connect
13	VCC3_3			3.3V Module Power
14		N/C		No Connect
15		N/C		No Connect
16		N/C		No Connect
17		N/C		No Connect
18		N/C		No Connect
19		N/C		No Connect
20	RSVD	N/C		Reserved – No Connect
21		N/C		No Connect
22	RSVD	N/C		Reserved – No Connect
23		N/C		No Connect
24	RSVD	N/C		Reserved – No Connect
25		N/C		No Connect
26	SYS_RST_L	I	VDDIO	Resets the radio, active low. Will be held low for ~700nSec by a RC reset circuit when power is applied. Do not connect when not used. See Note 2.
27	SDIO_DATA_2	I/O	VDDIO	SDIO Data 2 – Internal pull-up. No external pull-up resistor required
28	WLAN_ACTIVE	0	VDDIO	Not Supported. Leave open (float).
29	VCC3_3			3.3V Module Power
30	GND			Ground
31	GND			Ground
32	RSVD	N/C		Reserved – No Connect
33		N/C		No Connect
34		N/C		No Connect
35		N/C		No Connect
36	BT_ACTIVE	Ι	VDDIO	Not Supported. Leave open (float).
37		N/C		No Connect
38		N/C		No Connect
39		N/C		No Connect
40		N/C		No Connect
41		N/C		No Connect

Datasheet



Pin Number	Pin Name	ı/o	Power Supply	Description
42	WL_LED_ACT	0	VDDIO	WLAN LED activity indicator $I_{OH} = 2mA max (VDDIO = 1.8V)$ $I_{OH} = 4mA max (VDDIO = 3.3V)$ See the LED Support note below.
43		N/C		No Connect
44		N/C		No Connect
45		N/C		No Connect
46		N/C		No Connect
47		N/C		No Connect
48	CHIP_PWD_L	I	VDDIO	Powers down the radio, active low; 4.7K pull-up resistor to VDDIO is internal to the MSD30AG Do not connect when not used. See Note 2.
49		N/C		No Connect
50	RSVD	N/C		Reserved – No Connect
51		N/C		No Connect
52	RSVD	N/C		Reserved – No Connect
53	RSVD	N/C		Reserved – No Connect
54	RSVD	N/C		Reserved – No Connect
55	SDIO_CMD	I/O	VDDIO	SDIO Command – Internal pull-up. Note: An additional 10 K ohm pull-up resistor is required in some cases for SDIO_CMD.
56	SDIO_CLK	Ι	VDDIO	SDIO Clock (25MHz max)
57	SDIO_DATA_0	I/O	VDDIO	SDIO Data 0 – Internal pull-up. No external pull-up required
58	SDIO_DATA_3	I/O	VDDIO	SDIO Data 3 – Internal pull-up. No external pull-up resistor required
59	SDIO_DATA_1	I/O	VDDIO	SDIO Data 1 – Internal pull-up. No external pull-up resistor required
60	GND			Ground

Note 1: LED Support

• WL_LED_ACT Implementation on the SSD30AG or MSD30AG:

– WL_LED_ACT has an internal pull-down, and thus is low when the radio is off (not powered).

Note: The SSD30AG and MSD30AG devices require the SD30AG driver release 3.3.3 and greater.

Driver control implementation (when enabled):

- WL_LED_ACT is set to VDDIO when the radio is associated to an AP.
- WL_LED_ACT is set low at all other times (not associated).

Datasheet



- **Note 2:** If the following lines are available on the radio you are integrating into your system, you must connect and control them with the host device.
 - CHIP_PWD_L
 - SYS_RST_L
 - BT_RST_L
 - VDDIO_DR

If the radio stays powered up and the host goes down or is reset, communications cannot be reestablished with the radio. The host SDIO controller must re-establish communication with the radio by reloading the radio firmware after a power-on or a reset.

6.1. MSD30AG and MSD40NBT Pin Comparison Table

Note: Click here for a pin comparison table for the MSD10AG, MSD30AG, and MSD40NBT devices.

	MSD30AG	MSD40NBT		MSD30AG	MSD40NBT
Pin #	Pin Name	Pin Name	Pin #	Pin Name	Pin Name
1	GND	GND	31	GND	GND
2	RSVD	BT_UART_TXD	32	RSVD	BT_RST_L
3	BT_PRIORITY	BT_PRIORITY	33	No Connect	No Connect
4	BT_FREQ	BT_GPIO_6	34	No Connect	No Connect
5	RSVD	BT_UART_RTS_N	35	No Connect	No Connect
6	RSVD	BT_UART_RXD	36	BT_ACTIVE	BT_ACTIVE
7	RSVD	BT_HOST_WAKE_B	37	No Connect	No Connect
8	WL_GPIO_1	WL_GPIO_1	38	No Connect	No Connect
9	RSVD	BT_LED_ACT	39	No Connect	No Connect
10	RSVD	BT_PCM_OUT	40	No Connect	No Connect
11	RSVD	BT_UART_CTS_N	41	No Connect	No Connect
12	RSVD	BT_WAKE_B	42	WL_LED_ACT	WL_LED_ACT
13	VCC3_3	VCC3_3	43	No Connect	No Connect
14	No Connect	No Connect	44	No Connect	No Connect
15	No Connect	No Connect	45	No Connect	No Connect
16	No Connect	No Connect	46	No Connect	No Connect
17	No Connect	No Connect	47	No Connect	No Connect
18	No Connect	No Connect	48	CHIP_PWD_L	CHIP_PWD_L
19	No Connect	No Connect	49	No Connect	No Connect
20	RSVD	BT_PCM_SYNC	50	RSVD	BT_GPIO_3
21	No Connect	No Connect	51	No Connect	No Connect
22	RSVD	BT_PCM_IN	52	RSVD	BT_GPIO_4
23	No Connect	No Connect	53	RSVD	BT_GPIO_7
24	RSVD	BT_PCM_CLK	54	RSVD	BT_GPIO_5

Datasheet



	MSD30AG	MSD40NBT		MSD30AG	MSD40NBT
Pin #	Pin Name	Pin Name	Pin #	Pin Name	Pin Name
25	No Connect	No Connect	55	SDIO_CMD	SDIO_CMD
26	SYS_RST_L	SYS_RST_L	56	SDIO_CLK	SDIO_CLK
27	SDIO_DATA_2	SDIO_DATA_2	57	SDIO_DATA_0	SDIO_DATA_0
28	WLAN_ACTIVE	WLAN_ACTIVE	58	SDIO_DATA_3	SDIO_DATA_3
29	VCC3_3	VCC3_3	59	SDIO_DATA_1	SDIO_DATA_1
30	GND	GND	60	GND	GND

7 MECHANICAL SPECIFICATIONS

7.1. Connector Overview

MSD30AG connector: Molex 54722-0607 60-pin connector

Mating connector (on board): Molex 55560-0607 60-pin connector

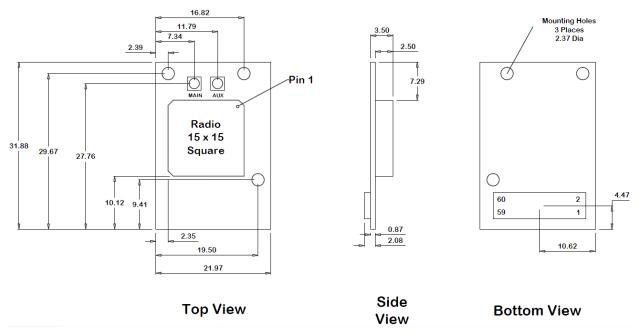


Figure 2: MSD30AG mechanical drawing

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7.1.1. SDC-MSD30AG Attached to T-Board

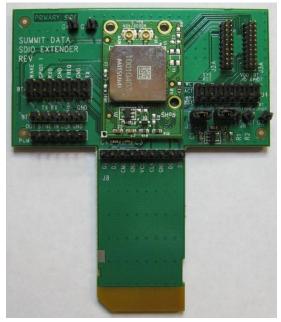
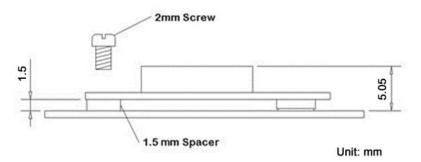


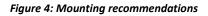
Figure 3: MSD30AG attached to T-board

7.2. Mounting

The SDC-MSD30AG connects to the host via a 60-pin connector. In addition, there are three mounting holes used to secure the device to the host using 2 mm mounting screws.

Laird recommends a 1.5 mm metal spacer (bushing) with a conductive mounting screw to connect the exposed ground pads of the radio circuit board to the host ground plane. A 1.5 mm conductive metal spacer with a maximum OD of 4 mm maximizes grounding of the radio and helps to reduce emissions from the radio circuit board. The spacer may also prevent the MSD board from slanting and breaking the connection to the host device when the board is attached to the host.





8 **RF LAYOUT DESIGN GUIDELINES**

The following is a list of RF layout design guidelines and recommendation when installing a Summit radio into your device.

• Do not run antenna cables directly above or directly below the radio.

Datasheet



- Do not place any parts or run any high speed digital lines below the radio.
- If there are other radios or transmitters located on the device (such as a Bluetooth radio), place the devices as far apart from each other as possible.
- Ensure that there is the maximum allowable spacing separating the antenna connectors on the Summit radio from the antenna. In addition, do not place antennas directly above or directly below the radio.
- Summit recommends the use of a double shielded cable for the connection between the radio and the antenna elements.
- Summit has provided three plated mounting holes that can be used for grounding. When additional ground
 plane is required, you may use some or all of these grounded mounting holes.

9 REGULATORY

9.1. Certified Antennas

The SDC-MSD30AG provides two Hirose U.FL type antenna connectors to support transmit and receive diversity. For single antenna, non-diversity applications, OEMs are advised to use the Main (not Aux) antenna connector and should disable transmit and receive diversity from the Global tab of the Summit Client Utility (SCU) software utility.

The SDC-MSD30AG has been tested to the regulatory standards defined in the "Certifications" section of the Specifications table above. These tests were conducted with the following antennas:

Cisco AIR-ANT 4941

- Form Factor: Whip
- Type: Dipole
- Maximum 2.4 GHz Gain: 2.2 dBi
- **Tested and Certified 2.4 GHz Transmit Power:** 100% of maximum setting (no reduction of power is required in the 2.4 GHz band)

Summit SDC-CF22G Antenna

- Form Factor: Chip Antenna on PCB
- Type: Dipole
- Maximum 2.4 GHz Gain: 0 dBi
- **Tested and Certified 2.4 GHz Transmit Power:** 100% of maximum setting (no reduction of power is required in the 2.4 GHz band)

Radiall Larson Dipole

- Form Factor: Whip
- Type: Dipole
- Maximum 2.4 GHz Gain: 1.6 dBi (not used during testing)
- Maximum 5 GHz Gain: 5 dBi
- **Tested and Certified 5 GHz Transmit Power:** 100% of maximum setting (no reduction of power is required in the 5 GHz band)

HUBER+SUHNER

- Form Factor: Whip
- **Type:** Monopole
- Maximum 2.4 GHz Gain: 3 dBi



- Maximum 5 GHz Gain: 6.5 dBi
- Tested and Certified 2.4 GHz Transmit Power: 100% of maximum setting (no reduction of power is required in the 2.4 GHz band)
- **Tested and Certified 5 GHz Transmit Power:** 100% of maximum setting (no reduction of power is required in the 5 GHz band)
- **Note:** The formal test reports for the SDC-MSD30AG show that transmit power was decreased to less than 100% on 2.4 GHz edge channels. Summit has made these transmit power reductions in firmware for the edge channels. Integrators do not need to reduce transmit power on a channel-by-channel basis to comply with band edge regulations.

Antennas of differing types and higher gains may be integrated as well. If necessary, with the Summit Manufacturing Utility software utility, OEMs may reduce the transmit power of the SDC-MSD30AG to account for higher antenna gain. In some cases, OEMs may be able to reduce certification efforts by using antennas that are of like type and equal or lesser gain to the above listed antennas.

9.2. Documentation Requirements

In order to maintain regulatory compliance, when integrating the SDC-MSD30AG into a host device and leveraging Summit's grants and certifications, it is necessary to meet the documentation requirements set forth by the applicable regulatory agencies. When leveraging Summit's grants, the following sections (FCC, Industry Canada, and European Union) outline the information that must be included in the user's guide and external labels for the host devices into which the SDC-MSD30AG is integrated.

9.2.1. FCC

User's Guide Requirements

As outlined in the Operational Description, the SDC-MSD30AG complies with FCC Part 15 Rules for a Limited Modular Approval. To leverage Summit's grant, the two conditions below must be met for the host device into which the SDC-MSD30AG is integrated:

- 1. The antenna is installed with 20 cm maintained between the antenna and users.
- 2. The transmitter module is not co-located with any other transmitter or antenna that is capable of simultaneous operation.

As long as the two conditions above are met, further *transmitter* testing is typically not required. However, the OEM integrator is still responsible for testing its end-product for any additional compliance requirements required with this module installed, such as (but not limited to) digital device emissions and PC peripheral requirements.

In the event that the two conditions above *cannot be met* (for example certain device configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID *cannot* be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

When using Laird's FCC grant for the SDC-MSD30AG, the integrator must include specific information in the user's guide for the device into which the SDC-MSD30AG is integrated. The integrator must not provide information to the end user regarding how to install or remove this RF module in the user's manual of the device into which the SDC-MSD30AG is integrated. The following FCC statements must be added in their



entirety and without modification into a prominent place in the user's guide for the device into which the SDC-MSD30AG is integrated:

"**IMPORTANT NOTE:** To comply with FCC RF exposure compliance requirements, the antenna used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operating in conjunction with any other antenna or transmitter."

Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- 1. Reorient or relocate the receiving antenna.
- 2. Increase the separation between the equipment and receiver.
- 3. Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- 4. Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

IMPORTANT NOTE: FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

Labeling Requirements

For FCC, the end product must be labeled in a visible area with the following notice:

Contains FCC ID: TWG-SDCMSD30AG

9.2.2. Industry Canada

User's Guide Requirements

As outlined in the Operational Description, the SDC-MSD30AG complies with Industry Canada (IC) rules for a Limited Modular Approval. To leverage Summit's grant, the two conditions below must be met for the host device into which the SDC-MSD30AG is integrated:

1. The antenna is installed with 20 cm maintained between the antenna and users.



2. The transmitter module is not co-located with any other transmitter or antenna that is capable of simultaneous operation.

As long as the two conditions above are met, further *transmitter* testing is typically not required. However, the OEM integrator is still responsible for testing its end-product for any additional compliance requirements required with this module installed, such as (but not limited to) digital device emissions and PC peripheral requirements.

In the event that the two conditions above *cannot be met* (for example certain device configurations or co-location with another transmitter), then the IC authorization is no longer considered valid and the IC ID *cannot* be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate IC authorization.

When using Summit's IC grant for the SDC-MSD30AG, the integrator must include specific information in the user's guide for the device into which the SDC-MSD30AG is integrated. The integrator must not provide information to the end user regarding how to install or remove this RF module in the user's manual of the device into which the SDC-MSD30AG is integrated. In addition to the required FCC statements outlined above, the following IC statements must be added in their entirety and without modification into a prominent place in the user's guide for the device into which the SDC-MSD30AG is integrated:

To prevent radio interference to the licensed service, this device is intended to be operated indoors and away from windows to provide maximum shielding. Equipment (or its transmit antenna) that is installed outdoors is subject to licensing.

The integrator must list out information for each antenna used with the host device into which the SDC-MSD30AG is integrated. The following examples are based on antennas with which the SDC-MSD30AG was certified and represent an acceptable format:

AIR-ANT 4941

- Form Factor: Whip
- Type: Dipole
- Maximum 2.4 GHz Gain: 2.2 dBi

Radiall Larson Dipole

- Form Factor: Whip
- Type: Dipole
- Maximum 2.4 GHz Gain: 1.6 dBi (not used during testing)
- Maximum 5 GHz Gain: 5 dBi

HUBER+SUHNER

- Form Factor: Whip
- Type: Monopole
- Maximum 2.4 GHz Gain: 3 dBi
- Maximum 5 GHz Gain: 6.5 dBi

Labeling Requirements

The final end product must be labeled in a visible area with the following notice:

Contains IC ID: 6616A-SDCMSD30AG



9.2.3. European Union

Declaration of Conformity

This device complies with the essential requirements of the Radio Equipment directive: 2014 / 53 / EU. The following test methods have been applied to prove presumption of conformity with the essential requirements of the Radio Equipment directive: **2014/53/EU**:

Manufacturer	Laird	
Products	MSD30AG Note: All MSD30AG certifications SSD30AG apply to the SSD30AG	
Product Description	802.11 a/b/g Enterprise Wi-Fi module	4.90
EU Directives	CO.	

Reference standards used for presumption of conformity:

Article Number	Requirement	Reference standard(s)
2.1.5	Low voltage equipment safety	EN 60950-1:2006 +A11:2009 +A1:2010 +A12:2011 +A2:2013
3.1a	RF Exposure	EN 62311:2008
3.1b	2004/108/EC Protection requirements with respect to electromagnetic compatibility	EN 301 489-1 v2.2.0 (2017-03) EN 301 489-17 v3.2.0 (2017-03)
3.2	Protection requirements – Electromagnetic compatibility	EN 300 328 v2.1.1 (2016-11) EN 301 893 v2.1.1 (2017-05)

Declaration:

We, Laird, declare under our sole responsibility that the essential radio test suites have been carried out and that the above product to which this declaration relates is in conformity with all the applicable essential requirements of Article 3 of the EU Directive 2014/53/EU, when used for its intended purpose.

Place of Issue:	Laird W66N220 Commerce Court, Cedarburg, WI 53012 USA tel: +1-262-375-4400 fax: +1-262-364-2649
Date of Issue:	June 2017
Name of Authorized Person:	Thomas T Smith, Director of EMC Compliance
Signature of Authorized Person:	Thomas T. Smith

Laird

Software Version for Testing

SW version: 35.9.1.12

MSD30AG

Datasheet

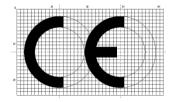
Maximum Output Power for Each Frequency

19.00 dBm, 2.412-2.472 GHz	18.00 dBm, 5.25-5.35 GHz
19.00 dBm, 5.15-5.25 GHz	18.00 dBm, 5.47-5.725 GHz

The minimum distance between the user and/or any bystander and the radiating structure of the transmitter is 20 cm.

5150 ~ 5350 MHz is limited to indoor used in the following countries:

_						LU					
!	BG	DE	EL	HR	LV	HU	AT	RO	FI	LI	TR
						MT					



User's Guide Requirements

The integrator must include specific information in the user's guide for the device into which the SDC-MSD30AG is integrated. In addition to the required FCC and IC statements outlined above, the following RED statements must be added in their entirety and without modification into a prominent place in the user's guide for the device into which the SDC-MSD30AG is integrated:

This device complies with the essential requirements of the Radio Equipment Directive: 2014/53/EU. The following test methods have been applied in order to prove presumption of conformity with the essential requirements of this directive:

• EN 60950-1:2006 +A11:2009 +A1:2010

Safety of Information Technology Equipment

• EN 300 328 v2.1.1

Electromagnetic compatibility and Radio spectrum Matters (ERM); Wideband Transmission systems; Data transmission equipment operating in the 2,4 GHz ISM band and using spread spectrum modulation techniques; Harmonized EN covering essential requirements under article 3.2 of the R&TTE Directive

EN 301 489-1 v2.2.0

Electromagnetic compatibility and Radio Spectrum Matters (ERM); ElectroMagnetic Compatibility (EMC) standard for radio equipment and services; Part 1: Common technical requirements

• EN 301 489-17 3.2.0

Electromagnetic compatibility and Radio spectrum Matters (ERM); ElectroMagnetic Compatibility (EMC) standard for radio equipment and services; Part 17: Specific conditions for 2,4 GHz wideband transmission systems and 5 GHz high performance RLAN equipment

• EN 301 893 v2.1.1

Electromagnetic compatibility and Radio spectrum Matters (ERM); Broadband Radio Access Networks (BRAN); Specific conditions for 5 GHz high performance RLAN equipment

• EU 2011/65/EU (RoHS)

Declaration of Compliance – EU Directive 2011/65/EU; Reduction of Hazardous Substances (RoHS)

This device is a 2.4 GHz wideband transmission system (transceiver), intended for use in all EU member states and EFTA countries, except in France and Italy where restrictive use applies.

Datasheet



In Italy the end-user should apply for a license at the national spectrum authorities in order to obtain authorization to use the device for setting up outdoor radio links and/or for supplying public access to MICommunications and/or network services.

This device may not be used for setting up outdoor radio links in France and in some areas the RF output power may be limited to 10 mW EIRP in the frequency range of 2454 – 2483.5 MHz. For detailed information the end-user should contact the national spectrum authority in France.

د Česky [Czech]	[Jméno výrobce] tímto prohlašuje, že tento [typ zařízení] je ve shodě se základními požadavky a dalšími příslušnými ustanoveními směrnice 1999/5/ES.
da [Danish]	Undertegnede [fabrikantens navn] erklærer herved, at følgende udstyr [udstyrets typebetegnelse] overholder de væsentlige krav og øvrige relevante krav i direktiv 1999/5/EF.
de Deutsch [German]	Hiermit erklärt <i>[Name des Herstellers],</i> dass sich das Gerät <i>[Gerätetyp]</i> in Übereinstimmung mit den grundlegenden Anforderungen und den übrigen einschlägigen Bestimmungen der Richtlinie 1999/5/EG befindet.
et Eesti [Estonian]	Käesolevaga kinnitab [tootja nimi = name of manufacturer] seadme [seadme tüüp = type of equipment] vastavust direktiivi 1999/5/EÜ põhinõuetele ja nimetatud direktiivist tulenevatele teistele asjakohastele sätetele.
en English	Hereby, [name of manufacturer], declares that this [type of equipment] is in compliance with the essential requirements and other relevant provisions of Directive 1999/5/EC.
es Español [Spanish]	Por medio de la presente <i>[nombre del fabricante]</i> declara que el <i>[clase de equipo]</i> cumple con los requisitos esenciales y cualesquiera otras disposiciones aplicables o exigibles de la Directiva 1999/5/CE.
^{el]} Ελληνική [Greek]	ΜΕ ΤΗΝ ΠΑΡΟΥΣΑ [name of manufacturer] ΔΗΛΩΝΕΙ ΟΤΙ [type of equipment] ΣΥΜΜΟΡΦΩΝΕΤΑΙ ΠΡΟΣ ΤΙΣ ΟΥΣΙΩΔΕΙΣ ΑΠΑΙΤΗΣΕΙΣ ΚΑΙ ΤΙΣ ΛΟΙΠΕΣ ΣΧΕΤΙΚΕΣ ΔΙΑΤΑΞΕΙΣ ΤΗΣ ΟΔΗΓΙΑΣ 1999/5/ΕΚ.
fr Français [French]	Par la présente [<i>nom du fabricant</i>] déclare que l'appareil [<i>type d'appareil</i>] est conforme aux exigences essentielles et aux autres dispositions pertinentes de la directive 1999/5/CE.
it Italiano [Italian]	Con la presente [nome del costruttore] dichiara che questo [tipo di apparecchio] è conforme ai requisiti essenziali ed alle altre disposizioni pertinenti stabilite dalla direttiva 1999/5/CE.
Latviski [Latvian]	Ar šo [name of manufacturer / izgatavotāja nosaukums] deklarē, ka [type of equipment / iekārtas tips] atbilst Direktīvas 1999/5/EK būtiskajām prasībām un citiem ar to saistītajiem noteikumiem.
Lietuvių [Lithuanian]	Šiuo [<i>manufacturer name</i>] deklaruoja, kad šis [<i>equipment type</i>] atitinka esminius reikalavimus ir kitas 1999/5/EB Direktyvos nuostatas.
nl Nederlands [Dutch]	Hierbij verklaart [<i>naam van de fabrikant</i>] dat het toestel [<i>type van toestel</i>] in overeenstemming is met de essentiële eisen en de andere relevante bepalingen van richtlijn 1999/5/EG.
^{mt} Malti [Maltese]	Hawnhekk, <i>[isem tal-manifattur],</i> jiddikjara li dan <i>[il-mudel tal-prodott]</i> jikkonforma mal- ħtiġijiet essenzjali u ma provvedimenti oħrajn relevanti li hemm fid-Dirrettiva 1999/5/EC.
^{hu} Magyar [Hungarian]	Alulírott, <i>[gyártó neve]</i> nyilatkozom, hogy a [típus] megfelel a vonatkozó alapvető követelményeknek és az 1999/5/EC irányelv egyéb előírásainak.

Datasheet



민 Polski	Niniejszym [<i>nazwa producenta</i>] oświadcza, że [<i>nazwa wyrobu</i>] jest zgodny z zasadniczymi
[Polish]	wymogami oraz pozostałymi stosownymi postanowieniami Dyrektywy 1999/5/EC.
₽t Português [Portuguese]	[Nome do fabricante] declara que este [tipo de equipamento] está conforme com os requisitos essenciais e outras disposições da Directiva 1999/5/CE.
डी Slovensko	[Ime proizvajalca] izjavlja, da je ta [tip opreme] v skladu z bistvenimi zahtevami in ostalimi
[Slovenian]	relevantnimi določili direktive 1999/5/ES.
Slovensky	<i>[Meno výrobcu]</i> týmto vyhlasuje, že <i>[typ zariadenia]</i> spĺňa základné požiadavky a všetky
[Slovak]	príslušné ustanovenia Smernice 1999/5/ES.
fi Suomi [Finnish]	[Valmistaja = manufacturer] vakuuttaa täten että [type of equipment = laitteen tyyppimerkintä] tyyppinen laite on direktiivin 1999/5/EY oleellisten vaatimusten ja sitä koskevien direktiivin muiden ehtojen mukainen.
^{डण} Svenska [Swedish]	Härmed intygar [<i>företag</i>] att denna <i>[utrustningstyp</i>] står I överensstämmelse med de väsentliga egenskapskrav och övriga relevanta bestämmelser som framgår av direktiv 1999/5/EG.

9.2.4. MIC

It is recommended that the host device bears a label showing the Japanese "GITEKI" mark and the certification number accompanied by the following statement:

当該機器には電波法に基づく、技術基準適合証明等を受けた特定無線設備を装着している

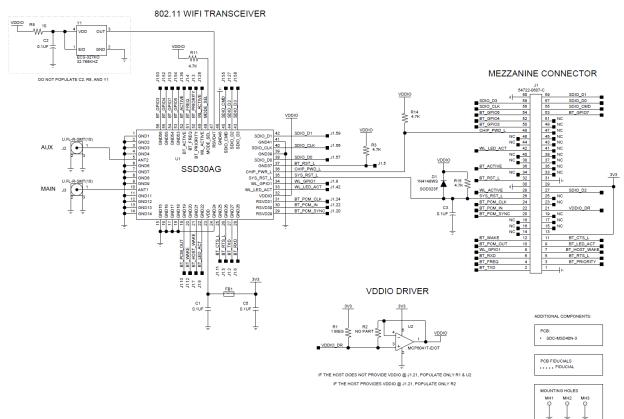
Translation: "This equipment contains specified radio equipment that has been certified to the Technical Regulation Conformity Certification under the Radio Law."

Datasheet



10 APPENDIX A: SCHEMATIC

The following SDC-MSD30AG schematic may be used as a reference.



				SHEET 1 OF	
CONTR NO			SIZE CAGE CODE DWG NO SDC-MSD3		REV
PROJ ENGR			Schematic		
DOON ENGR	M CLAUS	2/2010	SDC-MSD30AG Wirel	ess Modu	lle
снк	J POHMURSKI	3/2010			
DWN			SUMMIT		
_	SIGNATURE	DATE			
2	REMOVIED R9,	5/2010	M CLAI		
3	CHANGED TO :	6/2010	M CLAI		
4	CHANGED U1 S	10/2010	M CLAI		

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11 ADDITIONAL ASSISTANCE

Please contact your local sales representative or our support team for further assistance:

Laird Technologies Connectivity Products Business Unit Support Centre: http://ews-support.lairdtech.com

Email: wireless.support@lairdtech.com

Phone: Americas: +1-800-492-2320 Option 2 Europe: +44-1628-858-940 Hong Kong: +852 2923 0610

Web: http://www.lairdtech.com/bluetooth

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